

DAC0800/DAC0802 8-Bit Digital-to-Analog Converters

Check for Samples: [DAC0800](#), [DAC0802](#)

FEATURES

- **Fast Settling Output Current:** 100 ns
- **Full Scale Error:** ± 1 LSB
- **Nonlinearity Over Temperature:** $\pm 0.1\%$
- **Full Scale Current Drift:** ± 10 ppm/ $^{\circ}\text{C}$
- **High Output Compliance:** -10V to $+18\text{V}$
- **Complementary Current Outputs**
- **Interface Directly with TTL, CMOS, PMOS and Others**
- **2 Quadrant Wide Range Multiplying Capability**
- **Wide Power Supply Range:** $\pm 4.5\text{V}$ to $\pm 18\text{V}$
- **Low Power Consumption:** 33 mW at $\pm 5\text{V}$
- **Low Cost**

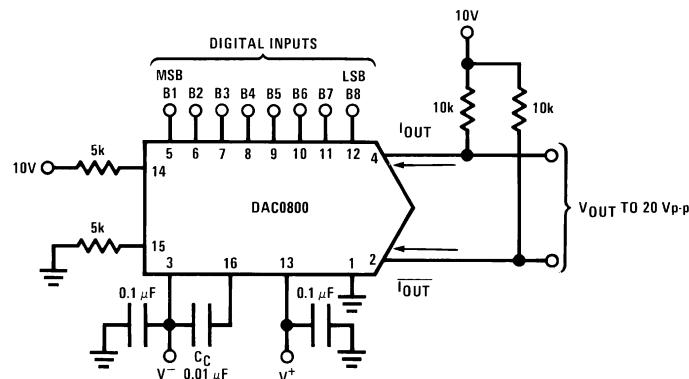
DESCRIPTION

The DAC0800 series are monolithic 8-bit high-speed current-output digital-to-analog converters (DAC) featuring typical settling times of 100 ns. When used as a multiplying DAC, monotonic performance over a 40 to 1 reference current range is possible. The DAC0800 series also features high compliance complementary current outputs to allow differential output voltages of 20 V_{p-p} with simple resistor loads. The reference-to-full-scale current matching of better than ± 1 LSB eliminates the need for full-scale trims in most applications, while the nonlinearities of better than $\pm 0.1\%$ over temperature minimizes system error accumulations.

The noise immune inputs will accept a variety of logic levels. The performance and characteristics of the device are essentially unchanged over the $\pm 4.5\text{V}$ to $\pm 18\text{V}$ power supply range and power consumption at only 33 mW with $\pm 5\text{V}$ supplies is independent of logic input levels.

The DAC0800, DAC0802, DAC0800C and DAC0802C are a direct replacement for the DAC-08, DAC-08A, DAC-08C, and DAC-08H, respectively. For single supply operation, refer to AN-1525.

Typical Application



Pin numbers represent the PDIP package. The SOIC package pin numbers differ from that of the PDIP package.

Figure 1. ± 20 V_{p-p} Output Digital-to-Analog Converter



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.



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Absolute Maximum Ratings ⁽¹⁾

| | |
|--|---------------------------------|
| Supply Voltage ($V^+ - V^-$) | $\pm 18V$ or $36V$ |
| Power Dissipation ⁽²⁾ | 500 mW |
| Reference Input Differential Voltage (V14 to V15) | V^- to V^+ |
| Reference Input Common-Mode Range (V14, V15) | V^- to V^+ |
| Reference Input Current | 5 mA |
| Logic Inputs | V^- to V^- plus $36V$ |
| Analog Current Outputs ($V_{S^-} = -15V$) | 4.25 mA |
| ESD Susceptibility ⁽³⁾ | TBD V |
| Storage Temperature | $-65^\circ C$ to $+150^\circ C$ |
| Lead Temp. (Soldering, 10 seconds) | |
| PDIP Package (plastic) | $260^\circ C$ |
| CDIP Package (ceramic) | $300^\circ C$ |
| Surface Mount Package | |
| Vapor Phase (60 seconds) | $215^\circ C$ |
| Infrared (15 seconds) | $220^\circ C$ |

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. DC and AC electrical specifications do not apply when operating the device beyond its specified operating conditions.
- (2) The maximum junction temperature of the DAC0800 and DAC0802 is $125^\circ C$. For operating at elevated temperatures, devices in the CDIP package must be derated based on a thermal resistance of $100^\circ C/W$, junction-to-ambient, $175^\circ C/W$ for the molded PDIP package and $100^\circ C/W$ for the SOIC package.
- (3) Human body model, 100 pF discharged through a 1.5 k Ω resistor.

Operating Conditions ⁽¹⁾

| | Min | Max | Units |
|----------------------------|--------------|--------------|------------|
| Temperature (T_A) | | | |
| DAC0800L | -55 | +125 | $^\circ C$ |
| DAC0800LC | 0 | +70 | $^\circ C$ |
| DAC0802LC | 0 | +70 | $^\circ C$ |
| V^+ | $(V^-) + 10$ | $(V^-) + 30$ | V |
| V^- | -15 | -5 | V |
| I_{REF} ($V^- = -5V$) | 1 | 2 | mA |
| I_{REF} ($V^- = -15V$) | 1 | 4 | mA |

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. DC and AC electrical specifications do not apply when operating the device beyond its specified operating conditions.

Electrical Characteristics

The following specifications apply for $V_S = \pm 15V$, $I_{REF} = 2\text{ mA}$ and $T_{MIN} \leq T_A \leq T_{MAX}$ unless otherwise specified. Output characteristics refer to both I_{OUT} and \bar{I}_{OUT} .

| Parameter | | Test Conditions | DAC0802LC | | | DAC0800L/ DAC0800LC | | | Units |
|--------------------------|-----------------------------------|---|-----------|---------------|------------|------------------------|---------------|------------|----------|
| | | | Min | Typ | Max | Min | Typ | Max | |
| | Resolution | | 8 | 8 | 8 | 8 | 8 | 8 | Bits |
| | Monotonicity | | 8 | 8 | 8 | 8 | 8 | 8 | Bits |
| | Nonlinearity | | | | ±0.1 | | | ±0.19 | %FS |
| t_s | Settling Time | To ±½ LSB, All Bits Switched "ON" or "OFF", $T_A=25^\circ\text{C}$ | | 100 | 135 | | | | ns |
| | | DAC0800L | | | | 100 | 135 | | ns |
| | | DAC0800LC | | | | 100 | 150 | | ns |
| t_{PLH} , t_{PHL} | Propagation Delay | $T_A=25^\circ\text{C}$ | | | | | | | |
| | Each Bit | | | 35 | 60 | | 35 | 60 | ns |
| | All Bits Switched | | | 35 | 60 | | 35 | 60 | ns |
| TCI_{FS} | Full Scale Tempco | | | ±10 | ±50 | | ±10 | ±50 | ppm/°C |
| V_{OC} | Output Voltage Compliance | Full Scale Current Change <½ LSB, $R_{OUT}>20\text{ M}\Omega$, Typical | -10 | | 18 | -10 | | 18 | V |
| I_{FS4} | Full Scale Current | $V_{REF} = 10.000V$, $R_{14} = R_{15} = 5.000\text{ k}\Omega$, $T_A=25^\circ\text{C}$ | 1.984 | 1.992 | 2.00 | 1.94 | 1.99 | 2.04 | mA |
| I_{FSS} | Full Scale Symmetry | $I_{FS4} - I_{FS2}$ | | ±0.5 | ±4.0 | | ±1 | ±8.0 | µA |
| I_{ZS} | Zero Scale Current | | | 0.1 | 1.0 | | 0.2 | 2.0 | µA |
| I_{FSR} | Output Current Range | $V^- = -5V$ $V^- = -8V\text{ to }-18V$ | 0 0 | 2.0 2.0 | 2.1 4.2 | 0 0 | 2.0 2.0 | 2.1 4.2 | mA |
| V_{IL} V_{IH} | Logic Input Levels | $V_{LC} = 0V$ | | | 0.8 | | | 0.8 | V |
| | Logic "0" Logic "1" | | 2.0 | | | 2.0 | | | V |
| I_{IL} I_{IH} | Logic Input Current | $V_{LC} = 0V$ | | | | | | | |
| | Logic "0" Logic "1" | $-10V \leq V_{IN} \leq +0.8V$ $2V \leq V_{IN} \leq +18V$ | | -2.0 0.002 | -10 10 | | -2.0 0.002 | -10 10 | µA µA |
| V_{IS} | Logic Input Swing | $V^- = -15V$ | -10 | | 18 | -10 | | 18 | V |
| V_{THR} | Logic Threshold Range | $V_S = \pm 15V$ | -10 | | 13.5 | -10 | | 13.5 | V |
| I_{15} | Reference Bias Current | | | -1.0 | -3.0 | | -1.0 | -3.0 | µA |
| dI/dt | Reference Input Slew Rate | (Figure 26) | 4.0 | 8.0 | | 4.0 | 8.0 | | mA/µs |
| $PSSI_{FS+}$ | Positive Power Supply Sensitivity | $4.5V \leq V^+ \leq 18V$ | | 0.0001 | 0.01 | | 0.0001 | 0.01 | %/% |
| $PSSI_{FS-}$ | Negative Power Supply Sensitivity | $-4.5V \leq V^- \leq 18V$, $I_{REF} = 1\text{ mA}$ | | 0.0001 | 0.01 | | 0.0001 | 0.01 | %/% |
| I_+ I_- | Power Supply Current | $V_S = \pm 5V$, $I_{REF} = 1\text{ mA}$ | | 2.3 | 3.8 | | 2.3 | 3.8 | mA |
| | | | | -4.3 | -5.8 | | -4.3 | -5.8 | mA |
| I_+ I_- | Power Supply Current | $V_S = +5V, -15V$, $I_{REF} = 2\text{ mA}$ | | 2.4 | 3.8 | | 2.4 | 3.8 | mA |
| | | | | -6.4 | -7.8 | | -6.4 | -7.8 | mA |
| I_+ I_- | Power Supply Current | $V_S = \pm 15V$, $I_{REF} = 2\text{ mA}$ | | 2.5 | 3.8 | | 2.5 | 3.8 | mA |
| | | | | -6.5 | -7.8 | | -6.5 | -7.8 | mA |
| P_D | Power Consumption | $\pm 5V$, $I_{REF} = 1\text{ mA}$ | | 33 | 48 | | 33 | 48 | mW |
| | | $+5V, -15V$, $I_{REF} = 2\text{ mA}$ | | 108 | 136 | | 108 | 136 | mW |
| | | $\pm 15V$, $I_{REF} = 2\text{ mA}$ | | 135 | 174 | | 135 | 174 | mW |

Connection Diagrams

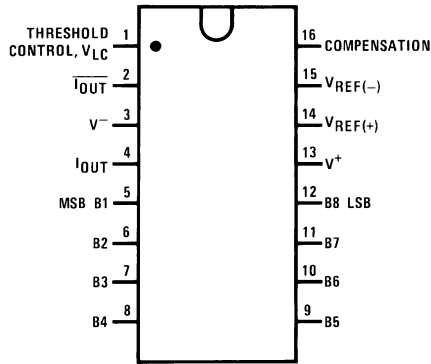


Figure 2. PDIP, CDIP Packages - Top View
(See Package Number NFG0016E or NFE0016A)

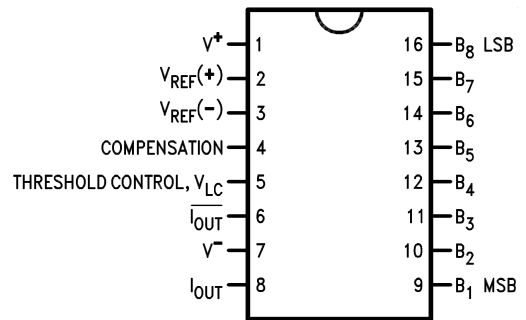
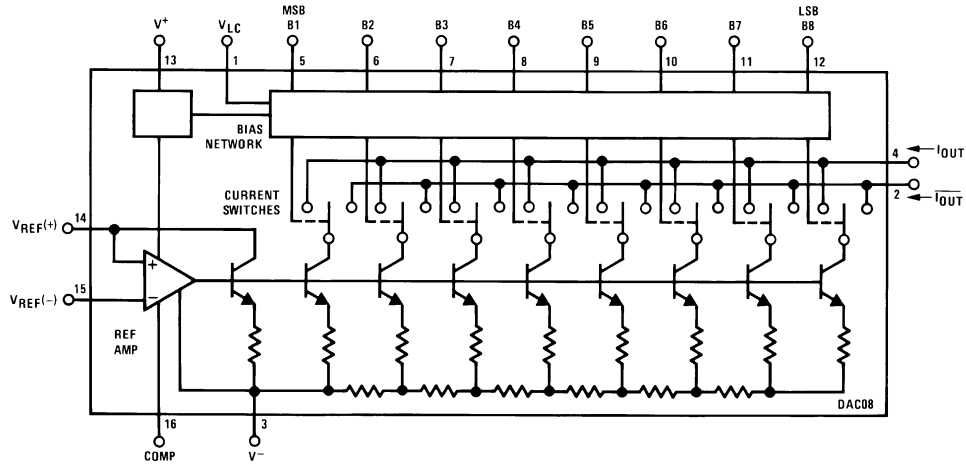


Figure 3. SOIC Package - Top View
(See Package Number D0016A)

Block Diagram



Pin numbers represent the PDIP package. The SOIC package pin numbers differ from that of the PDIP package.

Figure 4.

Typical Performance Characteristics

Full Scale Current vs. Reference Current

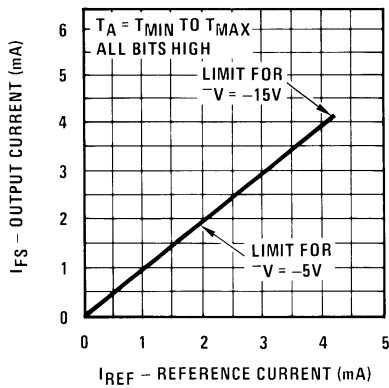


Figure 5.

LSB Propagation Delay vs. IFS

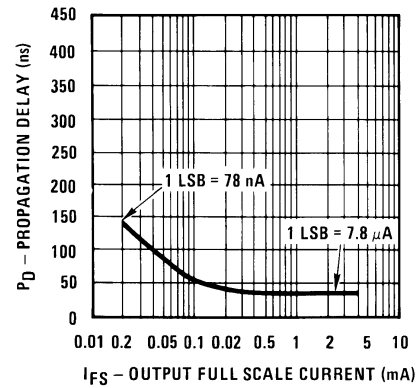
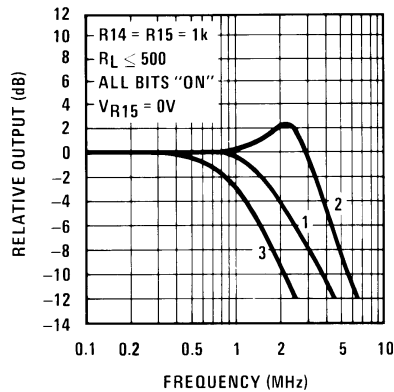


Figure 6.

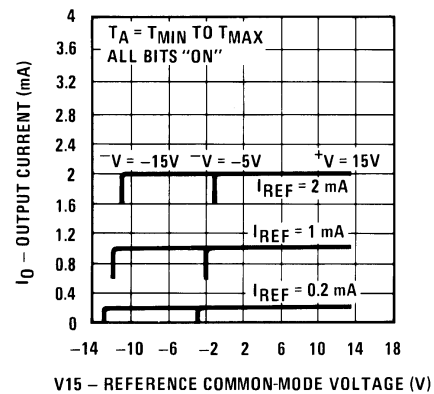
Reference Input Frequency Response



Curve 1: $C_C=15$ pF, $V_{IN}=2$ Vp-p centered at 1V.
 Curve 2: $C_C=15$ pF, $V_{IN}=50$ mVp-p centered at 200 mV.
 Curve 3: $C_C=0$ pF, $V_{IN}=100$ mVp-p centered at 0V and applied through 50Ω connected to pin 14. 2V applied to R14.

Figure 7.

Reference Amp Common-Mode Range



Note. Positive common-mode range is always $(V+) - 1.5V$.

Figure 8.

Logic Input Current vs. Input Voltage

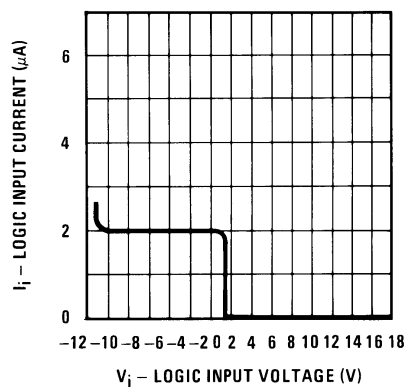


Figure 9.

$V_{TH} - V_{LC}$ vs. Temperature

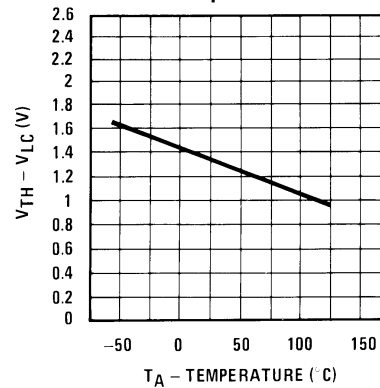


Figure 10.

Typical Performance Characteristics (continued)

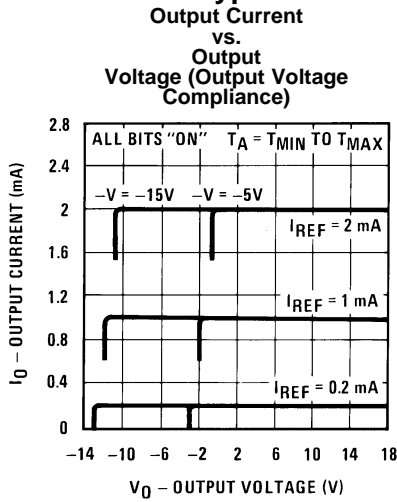


Figure 11.

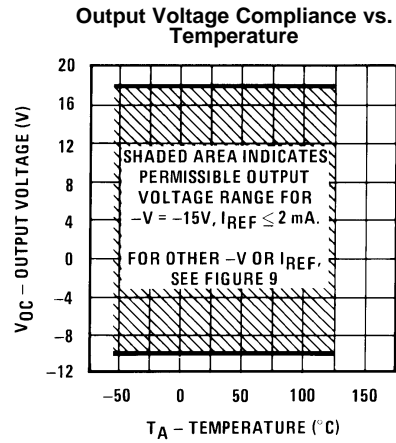
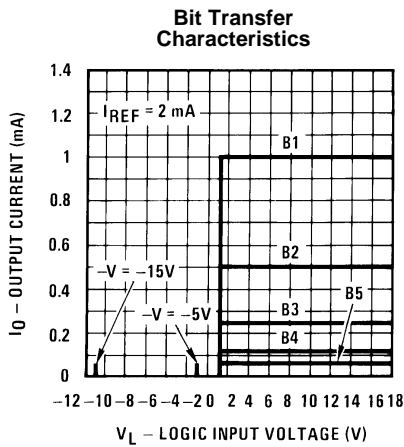


Figure 12.



Note. B1–B8 have identical transfer characteristics. Bits are fully switched with less than 1/2 LSB error, at less than ±100 mV from actual threshold. These switching points are guaranteed to lie between 0.8 and 2V over the operating temperature range ($V_{LC} = 0V$).

Figure 13.

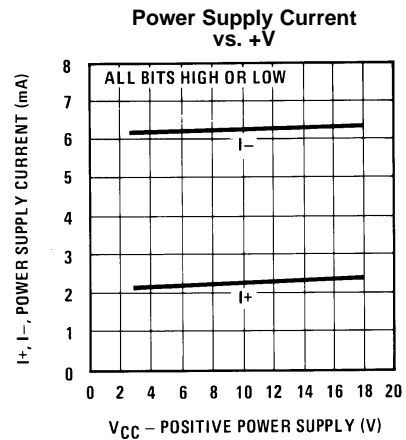


Figure 14.

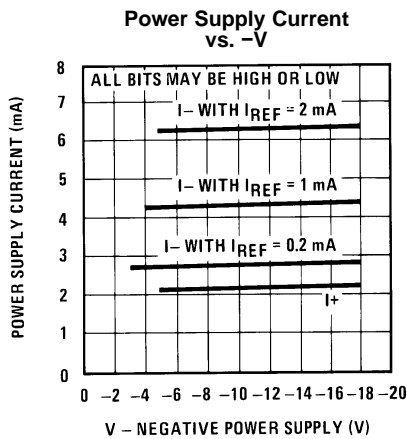


Figure 15.

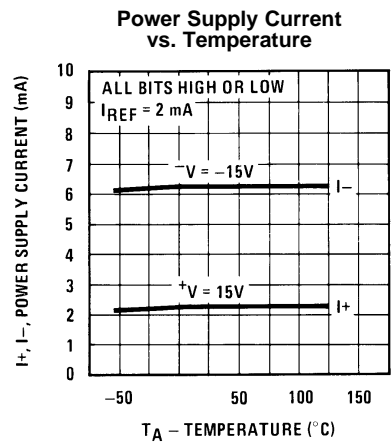


Figure 16.

EQUIVALENT CIRCUIT

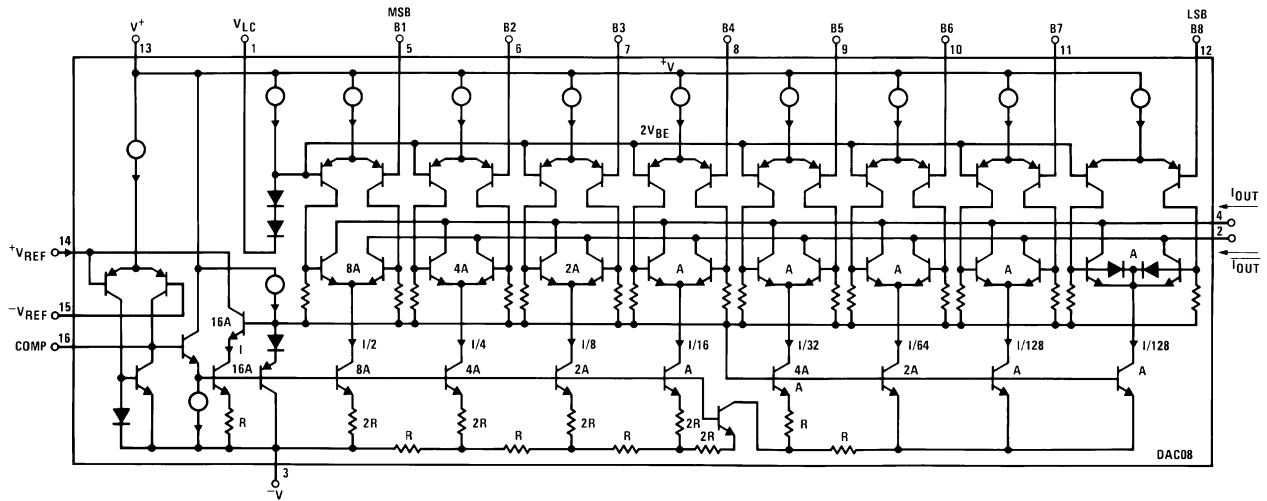
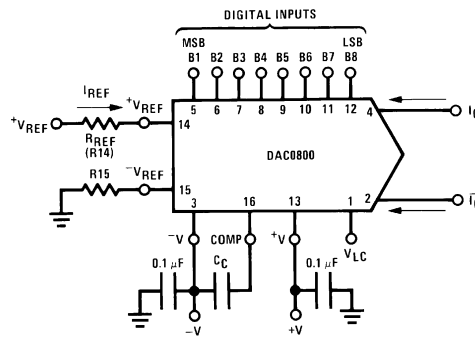


Figure 17. Equivalent Circuit

TYPICAL APPLICATIONS



Pin numbers represent the PDIP package. The SOIC package pin numbers differ from that of the PDIP package.

$$I_{FS} \approx \frac{+V_{REF}}{R_{REF}} \times \frac{255}{256}$$

$I_O + \bar{I}_O = I_{FS}$ for all logic states

For fixed reference, TTL operation, typical values are:

$V_{REF} = 10.000V$

$R_{REF} = 5.000k$

$R15 \approx R_{REF}$

$C_C = 0.01 \mu F$

$V_{LC} = 0V$ (Ground)

Figure 18. Basic Positive Reference Operation

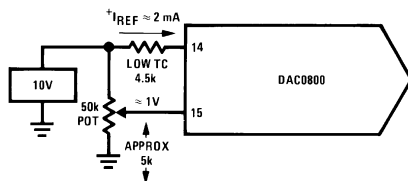


Figure 19. Recommended Full Scale Adjustment Circuit

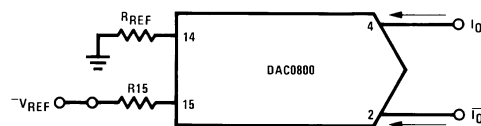
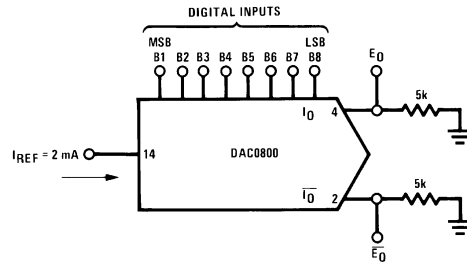


Figure 20. Basic Negative Reference Operation

Pin numbers represent the PDIP package. The SOIC package pin numbers differ from that of the PDIP package.

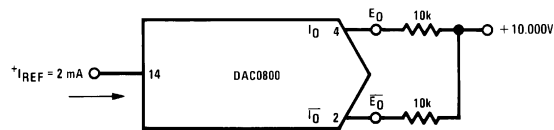


Pin numbers represent the PDIP package. The SOIC package pin numbers differ from that of the PDIP package.

Figure 21. Basic Unipolar Negative Operation

Table 1. Basic Unipolar Negative Operation

| | B1 | B2 | B3 | B4 | B5 | B6 | B7 | B8 | I _O mA | I _O -mA | E _O | E _O - |
|----------------|----|----|----|----|----|----|----|----|-------------------|--------------------|----------------|------------------|
| Full Scale | 1 | 1 | 1 | 1 | 1 | 1 | 1 | 1 | 1.992 | 0.000 | -9.960 | 0.000 |
| Full Scale-LSB | 1 | 1 | 1 | 1 | 1 | 1 | 1 | 0 | 1.984 | 0.008 | -9.920 | -0.040 |
| Half Scale+LSB | 1 | 0 | 0 | 0 | 0 | 0 | 0 | 1 | 1.008 | 0.984 | -5.040 | -4.920 |
| Half Scale | 1 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 1.000 | 0.992 | -5.000 | -4.960 |
| Half Scale-LSB | 0 | 1 | 1 | 1 | 1 | 1 | 1 | 1 | 0.992 | 1.000 | -4.960 | -5.000 |
| Zero Scale+LSB | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 1 | 0.008 | 1.984 | -0.040 | -9.920 |
| Zero Scale | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0.000 | 1.992 | 0.000 | -9.960 |

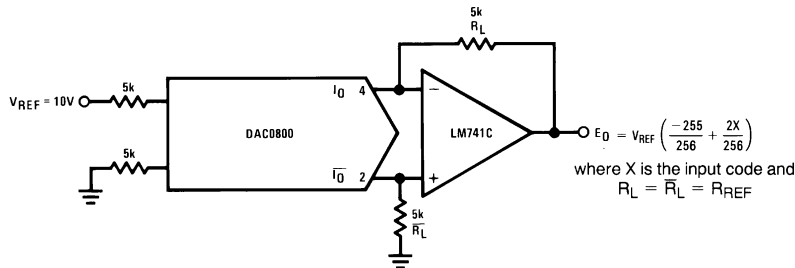


Pin numbers represent the PDIP package. The SOIC package pin numbers differ from that of the PDIP package.

Figure 22. Basic Bipolar Output Operation

Table 2. Basic Bipolar Output Operation

| | B1 | B2 | B3 | B4 | B5 | B6 | B7 | B8 | E _O | E _O - |
|---------------------|----|----|----|----|----|----|----|----|----------------|------------------|
| Pos. Full Scale | 1 | 1 | 1 | 1 | 1 | 1 | 1 | 1 | -9.920 | +10.000 |
| Pos. Full Scale-LSB | 1 | 1 | 1 | 1 | 1 | 1 | 1 | 0 | -9.840 | +9.920 |
| Zero Scale+LSB | 1 | 0 | 0 | 0 | 0 | 0 | 0 | 1 | -0.080 | +0.160 |
| Zero Scale | 1 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0.000 | +0.080 |
| Zero Scale-LSB | 0 | 1 | 1 | 1 | 1 | 1 | 1 | 1 | +0.080 | 0.000 |
| Neg. Full Scale+LSB | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 1 | +9.920 | -9.840 |
| Neg. Full Scale | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | +10.000 | -9.920 |

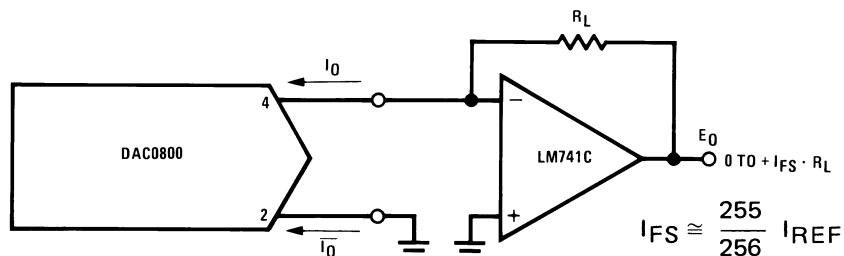


- (1) Pin numbers represent the PDIP package. The SOIC package pin numbers differ from that of the PDIP package.
- (2) If $R_L = \bar{R}_L$ within $\pm 0.05\%$, output is symmetrical about ground.

Figure 23. Symmetrical Offset Binary Operation

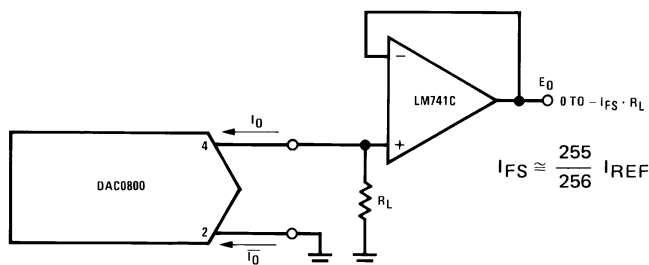
Table 3. Symmetrical Offset Binary Operation

| | B1 | B2 | B3 | B4 | B5 | B6 | B7 | B8 | E _O |
|---------------------|----|----|----|----|----|----|----|----|----------------|
| Pos. Full Scale | 1 | 1 | 1 | 1 | 1 | 1 | 1 | 1 | +9.960 |
| Pos. Full Scale-LSB | 1 | 1 | 1 | 1 | 1 | 1 | 1 | 0 | +9.880 |
| (+)Zero Scale | 1 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | +0.040 |
| (-)Zero Scale | 0 | 1 | 1 | 1 | 1 | 1 | 1 | 1 | -0.040 |
| Neg. Full Scale+LSB | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 1 | -9.880 |
| Neg. Full Scale | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | -9.960 |



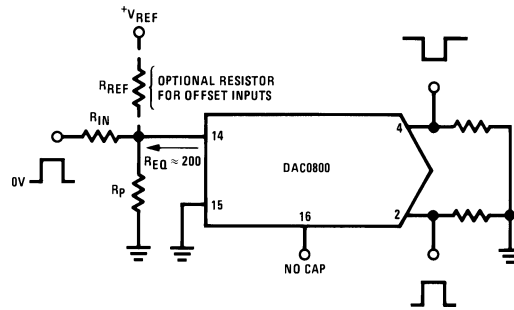
- (1) Pin numbers represent the PDIP package. The SOIC package pin numbers differ from that of the PDIP package.
- (2) For complementary output (operation as negative logic DAC), connect inverting input of op amp to \bar{I}_O (pin 2), connect I_O (pin 4) to ground.

Figure 24. Positive Low Impedance Output Operation



- (1) Pin numbers represent the PDIP package. The SOIC package pin numbers differ from that of the PDIP package.
- (2) For complementary output (operation as a negative logic DAC) connect non-inverting input of op am to \bar{I}_O (pin 2); connect I_O (pin 4) to ground.

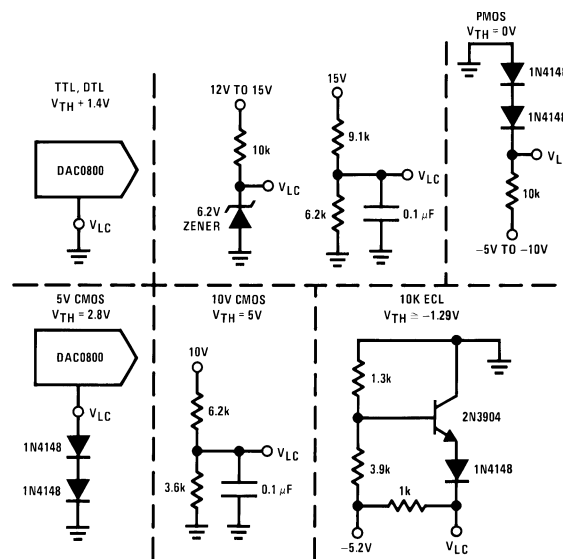
Figure 25. Negative Low Impedance Output Operation



Typical values: $R_{IN}=5k, +V_{IN}=10V$

Pin numbers represent the PDIP package. The SOIC package pin numbers differ from that of the PDIP package.

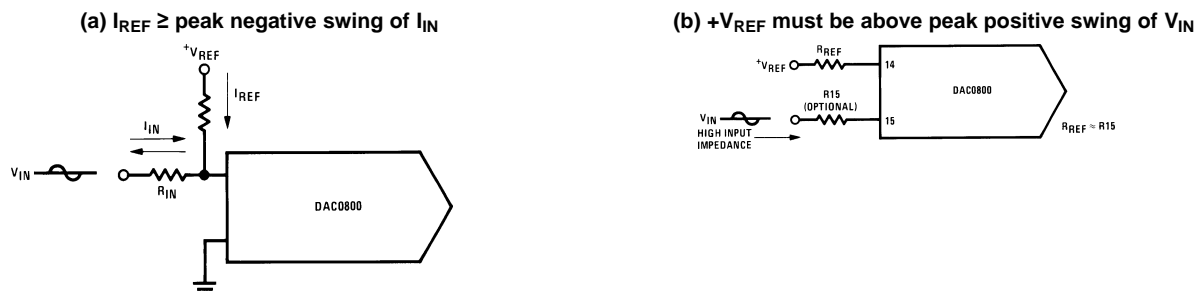
Figure 26. Pulsed Reference Operation



$V_{TH} = V_{LC} + 1.4V$
 15V CMOS, HTL, HNIL
 $V_{TH} = 7.6V$

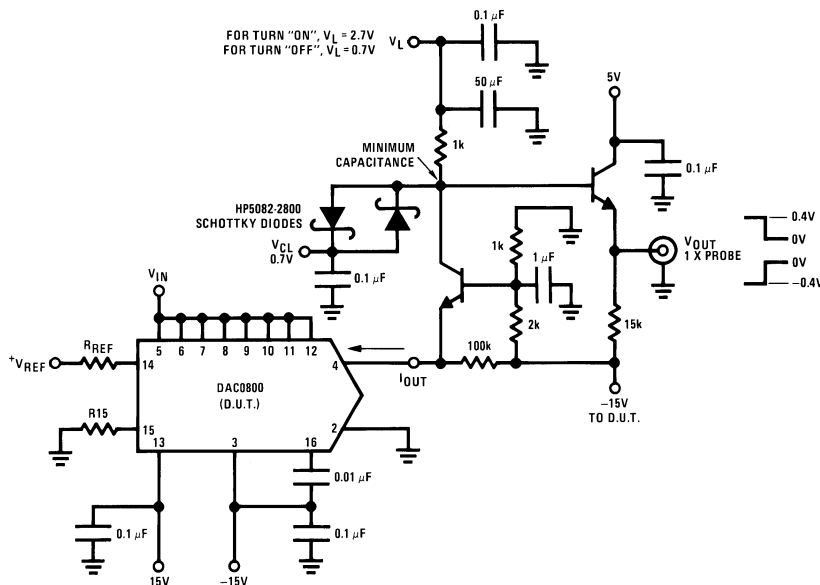
Note. Do not exceed negative logic input range of DAC.

Figure 27. Interfacing with Various Logic Families



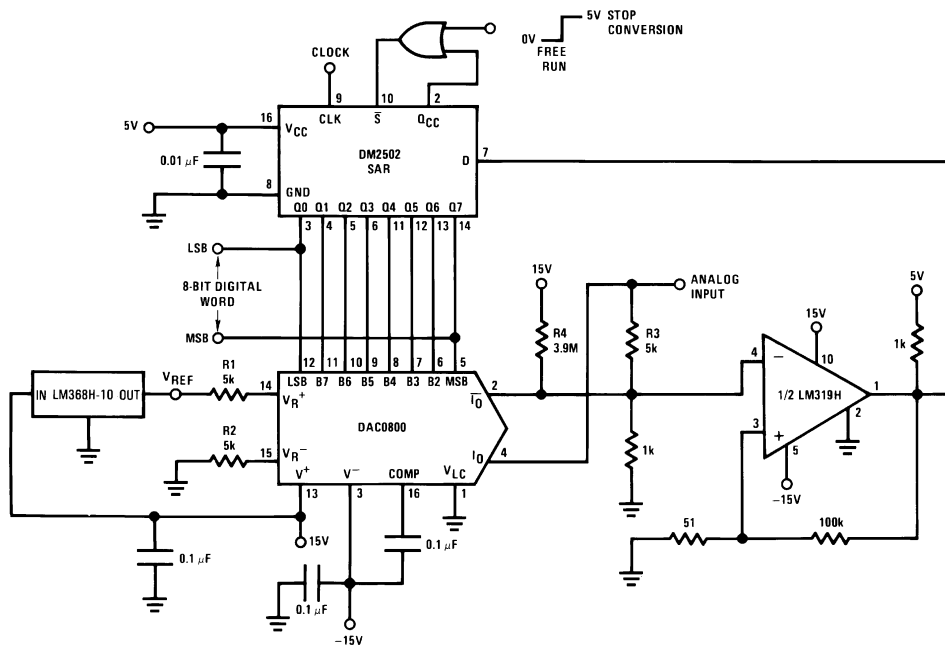
Pin numbers represent the PDIP package. The SOIC package pin numbers differ from that of the PDIP package.

Figure 28. Accommodating Bipolar References



Pin numbers represent the PDIP package. The SOIC package pin numbers differ from that of the PDIP package.

Figure 29. Settling Time Measurement



- (1) For 1 µs conversion time with 8-bit resolution and 7-bit accuracy, an LM361 comparator replaces the LM319 and the reference current is doubled by reducing R1, R2 and R3 to 2.5 kΩ and R4 to 2 MΩ.
- (2) Pin numbers represent the PDIP package. The SOIC package pin numbers differ from that of the PDIP package.

Figure 30. A Complete 2 µs Conversion Time, 8-Bit A/D Converter

REVISION HISTORY

| Changes from Revision B (February 2013) to Revision C | Page |
|--|--------------------------|
| <hr/> <ul style="list-style-type: none">• Changed layout of National Data Sheet to TI format | <hr/> 12 |

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead finish/ Ball material (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|------------------|--------------------------------------|----------------------|--------------|-------------------------|---------|
| DAC0800LCM | NRND | SOIC | D | 16 | 48 | Non-RoHS & Green | Call TI | Call TI | 0 to 70 | DAC0800LCM | |
| DAC0800LCM/NOPB | ACTIVE | SOIC | D | 16 | 48 | RoHS & Green | SN | Level-1-260C-UNLIM | 0 to 70 | DAC0800LCM | Samples |
| DAC0800LCMX/NOPB | ACTIVE | SOIC | D | 16 | 2500 | RoHS & Green | SN | Level-1-260C-UNLIM | 0 to 70 | DAC0800LCM | Samples |
| DAC0800LCN/NOPB | ACTIVE | PDIP | NFG | 16 | 25 | RoHS & Non-Green | SN | Level-1-NA-UNLIM | 0 to 70 | DAC0800LCN DAC-08EP | Samples |
| DAC0802LCMX | NRND | SOIC | D | 16 | 2500 | Non-RoHS & Green | Call TI | Call TI | 0 to 70 | DAC0802LCM | |
| DAC0802LCMX/NOPB | ACTIVE | SOIC | D | 16 | 2500 | RoHS & Green | SN | Level-1-260C-UNLIM | 0 to 70 | DAC0802LCM | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

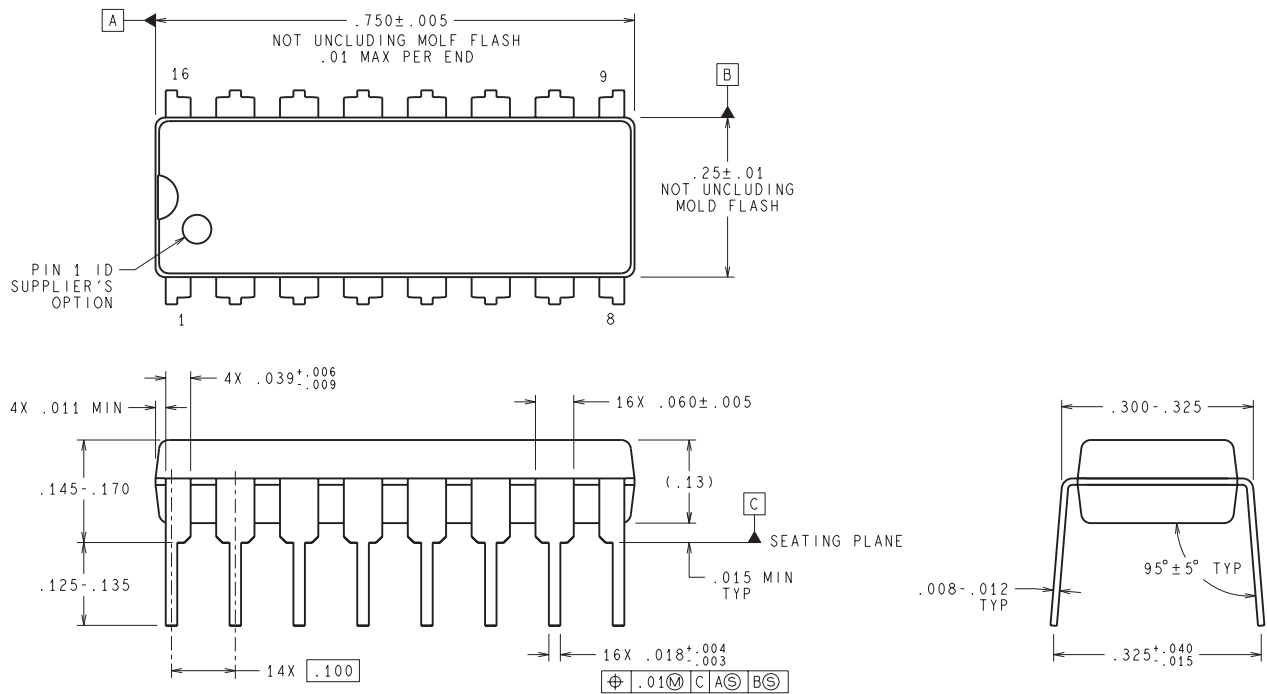
| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|------------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| DAC0800LCMX/NOPB | SOIC | D | 16 | 2500 | 330.0 | 16.4 | 6.5 | 10.3 | 2.3 | 8.0 | 16.0 | Q1 |
| DAC0802LCMX | SOIC | D | 16 | 2500 | 330.0 | 16.4 | 6.5 | 10.3 | 2.3 | 8.0 | 16.0 | Q1 |
| DAC0802LCMX/NOPB | SOIC | D | 16 | 2500 | 330.0 | 16.4 | 6.5 | 10.3 | 2.3 | 8.0 | 16.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|------------------|--------------|-----------------|------|------|-------------|------------|-------------|
| DAC0800LCMX/NOPB | SOIC | D | 16 | 2500 | 367.0 | 367.0 | 35.0 |
| DAC0802LCMX | SOIC | D | 16 | 2500 | 367.0 | 367.0 | 35.0 |
| DAC0802LCMX/NOPB | SOIC | D | 16 | 2500 | 367.0 | 367.0 | 35.0 |

NFG0016E

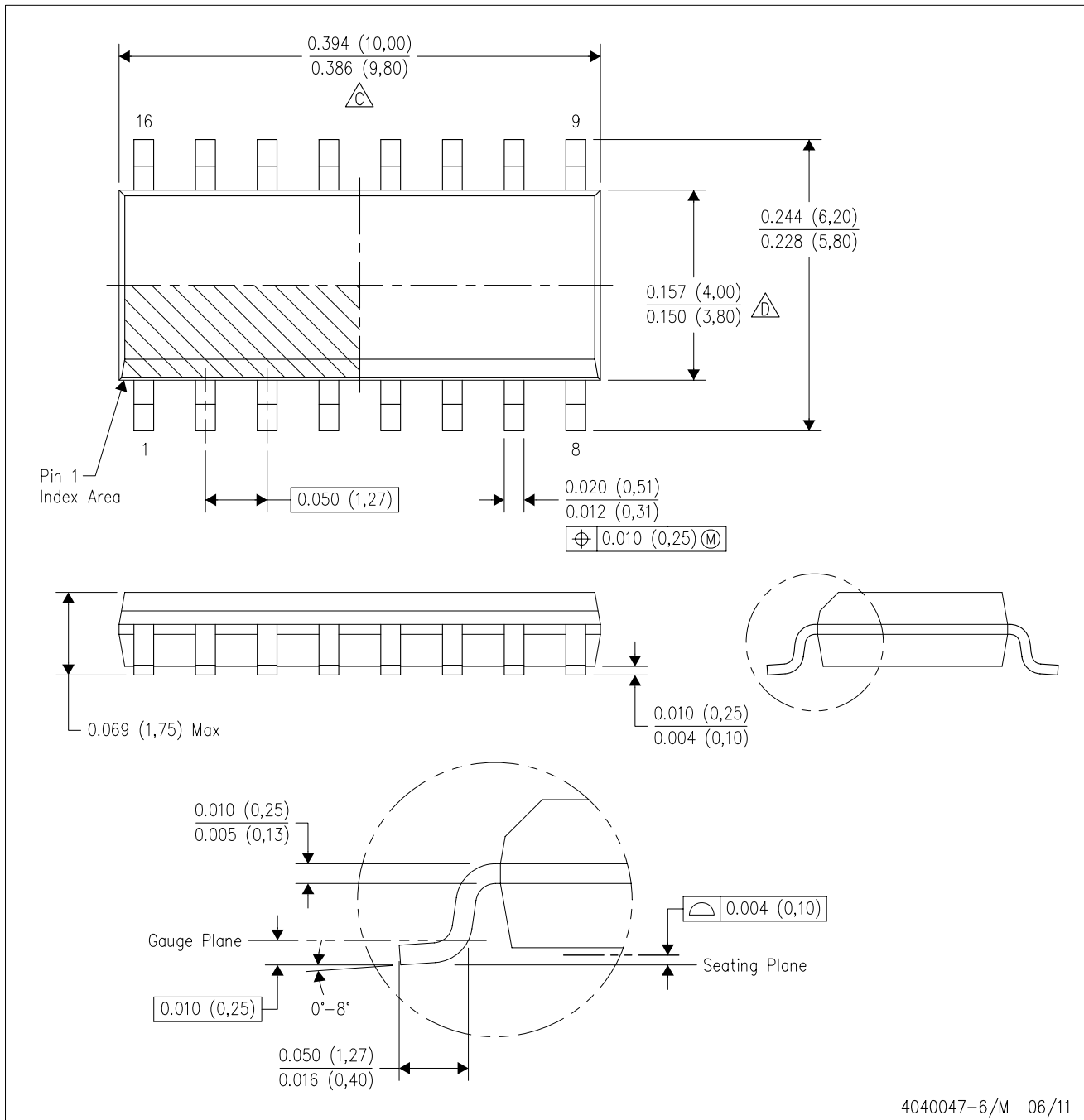


DIMENSIONS ARE IN INCHES
DIMENSIONS IN () FOR REFERENCE ONLY

N16E (Rev G)

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.

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